

CLAIMS

What is claimed is:

- Sub A
1. A heat exchanger for a semiconductor chip comprising:
a heat conducting surface positioned adjacent said semiconductor chip;
a circular chamber positioned above the heat conducting surface;
a plurality of heat conducting fins disposed within the circular chamber;
a fluid inlet aperture positioned at a central portion of the of the circular chamber; and
a fluid outlet aperture positioned at a peripheral region of the circular chamber.
 - Sub B 2. The heat exchanger of claim 1 wherein the plurality of fins are positioned in a generally radial direction extending from a central region of the circular chamber towards a peripheral region;
 3. The heat exchanger of claim 1 wherein the fins are arranged in a spiral pattern, each fin extending from a central area of the chamber out toward a peripheral portion of the chamber.
 4. The heat exchanger assembly of claim 1 wherein the circular chamber comprises an overhead wall and there is at least one annular channel recessed upwardly into the overhead wall.
 5. The heat exchanger of claim 3 wherein each fin extends laterally from a leading edge to a trailing edge with the trailing edge being closer to the peripheral portion of the circular chamber, and the fin being laterally straight.
 6. The heat exchanger of claim 3 wherein each fin extends laterally from a leading edge to a trailing edge with the trailing edge being closer to the peripheral portion of the circular chamber, and the fin being laterally curved in the direction of the spiral pattern

7. The heat exchanger of claim 3 wherein an outer perimeter of the circular chamber is defined by the inside surface of an annular wall, and there is at least one annular space in the chamber proximate the annular wall, between a trailing edge of the fins and the annular wall.

8. The heat exchanger of claim 7 wherein an overhead wall of the circular chamber has at least one annular fluid channel recessed upwardly into the wall.

9. The heat exchanger of claim 8 wherein the annular channel of the overhead wall has a varying cross sectional area with the area being greatest at a distance furthest from the fluid outlet aperture and the area being at a minimum adjacent the fluid outlet aperture.

10. The heat exchanger of claim 1 wherein the fins are arranged in at least two concentric circular arrays, comprising at least an inner array and at least an outer array, each circular array comprising a plurality of fins arranged in a generally radial pattern with each fin extending from a leading edge of the fin to a trailing edge of the fin, the trailing edge being positioned radially outward of the leading edge closer to a peripheral region of the circular chamber.

11. The heat exchanger of claim 10 wherein the fins of each circular array are arranged in a spiral pattern, each fin have a leading edge and a trailing edge, with the trailing edges of the fins being positioned closer to a peripheral region of the circular chamber than leading edges.

12. The heat exchanger of claim 10 wherein the circular chamber has at least two annular space regions, with at least a first annular space being between the inner array and outer array of fins, and at least a second annular space being between the outer array of fins and an inside surface of an annular wall of the chamber.

13. The heat exchanger according to claim 12 wherein an overhead wall of the circular chamber has at least one annular fluid channel recessed upwardly into the wall, the annular fluid channel being disposed over at least one of the annular space regions in the circular chamber.

14. The heat exchanger of claim 13 wherein the annular fluid channel has a varying cross sectional area, the cross sectional area being greatest at a distance along the channel furthest from the fluid outlet aperture and at a minimum adjacent the fluid outlet aperture.

15. The heat exchanger of claim 2 wherein an outer portion of the circular chamber, has a varying cross sectional area.

16. The heat exchanger of claim 15 wherein the cross section area of the outer portion of the chamber is greatest at a position diametrically opposed to the position of the fluid outlet aperture.

17. The heat exchanger of claim 2 wherein the fluid inlet aperture is positioned in overhead wall of the circular chamber at the center of the wall and the fluid outlet aperture is positioned in the overhead wall at the periphery of the wall.

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18. A heat exchanger for a semiconductor chip comprising:
a heat conducting surface;
a fin plate having an array of fins arranged in a generally radial pattern, extending outward from a central region of the plate toward a peripheral region of the plate;
an annular wall extending upwardly from the fin plate;
an overhead wall with a recessed annular channel, the overhead wall, the fin plate and the annular wall defining a fluid chamber of the heat exchanger;
a fluid inlet aperture disposed at the center of the overhead wall; and

25. The heat exchanger assembly of claim 23 further comprising a bow spring configured to fit over the retaining plate, the bow spring also having a bore which is aligned with the bore of the retaining plate through which the fluid chamber is inserted and rotatably retained.

26. The heat exchanger assembly of claim 23 further comprising a spring configured and mounted on the retaining plate such that the restoring force of the spring is translated to the force between the heat conducting surface and an adjacent heat emitting surface when the spring is tightened.

27. The heat exchanger assembly of claim 26 wherein the means of tightening the spring also comprises the means of retaining the semiconductor package adjacent the heat conducting plate.

28. The heat exchanger assembly of claim 27 wherein the fluid chamber, the spring, the retaining assembly, and a means for tightening the spring are all configured to be captive in their respective positions but selectively movable for installation of the heat exchanger assembly so as to allow tightening or releasing of the spring tension, and rotating of the fluid chamber.

29. A method for cooling a semiconductor chip comprising:
impacting a cooling fluid against the central region of a plate within a circular chamber;
distributing the fluid through the chamber;
withdrawing heat from the semiconductor through the plate and into the fluid; and
discharging the fluid through an outlet aperture located at a peripheral portion of the circular chamber.

Sub 11 30. The method according to claim 29 wherein distribution of the fluid through the chamber comprises directing the fluid in a generally radial direction to the periphery of the circular chamber.

31. The method according to claim 29 wherein distribution of the fluid through the chamber comprises directing the fluid in a spiraling direction from the center of the plate towards the periphery of the circular chamber.

32. The method of claim 31 further comprising attaining even distribution of the fluid throughout the circular chamber as it flows towards the periphery of the chamber by equalizing pressure drop for substantially equal flows rates, from the center of the plate, in any radial direction, to the fluid outlet aperture of the chamber.

33. The method of claim 32 wherein equalizing the pressure drop from the center of the plate to the outlet aperture comprises varying the fluid velocity of the fluid about the periphery of the circular chamber.

34. The method of claim 33 wherein varying the fluid velocity about the periphery of the circular chamber further comprises increasing the fluid velocity as it approaches the fluid outlet aperture.

Sub 15 35. The method according to claim 32 wherein equalizing the pressure drop comprises varying the cross sectional area of an outer portion of the circular chamber.

Sub 15 36. The method of claim 29 further comprising increasing an individual heat transfer coefficient of the fluid by increasing turbulence and reducing boundary layer thickness of the fluid on a wall within the circular chamber by changing momentum of the fluid.

37. The method of claim 36 wherein changing the momentum of the fluid comprises directing the fluid in a curved spiral flow pattern.

38. The method of claim 29 further comprising attaining uniform distribution of the fluid through the chamber by spreading the fluid in a generally radial direction and reducing back pressure against the radial flow.

39. The method of claim 38 wherein reducing the back pressure against the radial flow comprises imparting rotational velocity to the fluid on the outer perimeter of the chamber.

40. The method of claim 29 further comprising attaining uniform distribution of the fluid through the chamber by spreading the fluid in a generally radial direction and creating a low pressure zone about the periphery of the chamber.

41. The method of claim 29 further comprising reducing boundary layer thickness on a heat transfer surface by introducing a space between two heat transfer walls wherein fluid communication with the walls is momentarily broken while the fluid travels between the walls.

42. The method of claim 29 further comprising increasing the overall heat transfer area by providing a curved heat transfer surface.

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